

CH03-CJ - SIM CARD HOLDER, CONTACT TYPE, WITHOUT SWITCH, 8 PINS

FEATURES

1. GENERAL CHARACTERISTICS

DIMENSIONS: 23.62L x 10.16W x 1.3H mm
 WEIGHT: APPROX. 0.5±0.1g
 CONTACT PRINCIPLE: FRICTION TECHNOLOGY
 MOUNTING SYSTEM: SMT TYPE OPTIONAL POST
 DURABILITY: 100,000 CYCLES MIN.

2. MECHANICAL CHARACTERISTICS

INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0
 CONTACT MATERIAL: PHOSPHOR BRONZE
 CONTACT AREA PLATING: GOLD FLASH OVER NICKEL

3. ELECTRICAL CHARACTERISTICS

CONTACT RESISTANCE: 50m OHMS TYP. 100m OHMS MAX.
 INSULATION RESISTANCE: >1000M OHMS / 500V DC
 RATED CURRENT: 1A MAX, 10uA MIN.
 RATED VOLTAGE: 50V MAX.
 WITHSTANDING DIELECTRIC VOLTAGE: 500V AC R.M.S. FOR 1 MINUTE

4. SOLDERABILITY

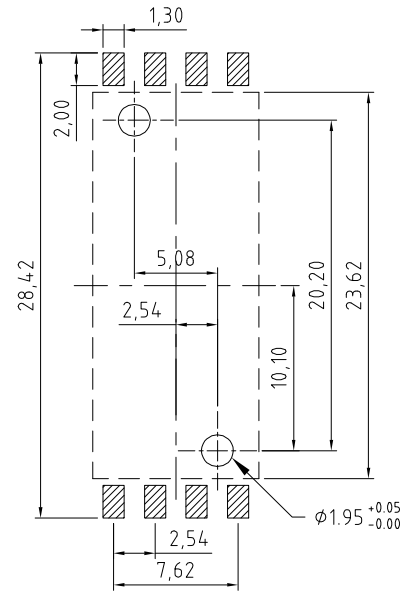
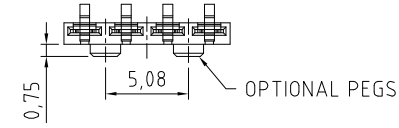
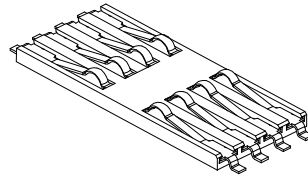
WAVE: NOT APPLICABLE
 IR REFLOW: 250°C, 5 SEC. MAX.
 MANUAL SOLDERING: 360°C, 3 SEC. MAX.

5. ENVIRONMENTAL CHARACTERISTICS

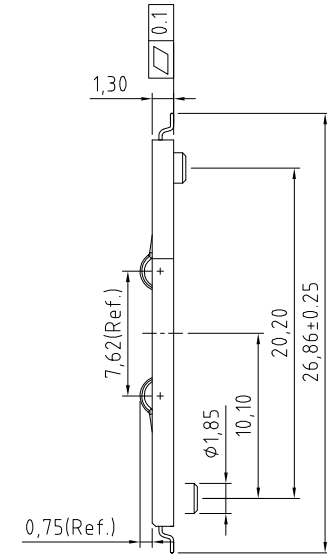
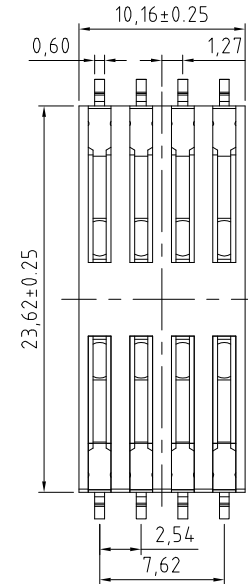
OPERATING TEMPERATURE: -40°C ~ +85°C
 OPERATING HUMIDITY: 10% ~ 95% RH
 STORAGE TEMPERATURE: -40°C ~ +85°C
 STORAGE HUMIDITY: 10% ~ 95% RH
 THERMAL SHOCK: -40°C ~ +85°C, 5 CYCLES
 DAMP HEAT: 40°C, 90% RH, 240HR
 SALT-MIST: 35°C, 5% NaCl, 24HR

NOTES:

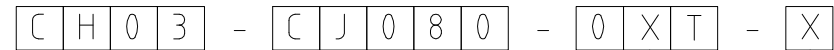
- ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.
- PACKAGING: 40PCS/TUBE.



COMPONENT SIDE (TOLERANCE: ±0.05)
 RECOMMENDED PCB LAYOUT



HOW TO ORDER



LOCATING PEG OPTIONS:
 A = WITH PEGS
 B = WITHOUT PEG

'H' HEIGHT OPTIONS:
 A = 1.30MM

REV. DATE & DRN
 10 26/10/11 - NYW RELEASE
 11 28/11/14 - NYW
 12 09/08/17 - NYW
 Δ AMEND PROFILE OPTION C → B.
 REMOVE PROFILE OPTION B

Scale: 3:1
 Drawn: NYW
 App'd: XXXX
 Date: 09 Aug. '17

THIRD ANGLE

 Title SIM CARD ACCEPTOR
 Revision: 1.2

Unstated Tolerances:
 X ±0.35
 .X ±0.25
 .XX ±0.15
 .XXX ±0.10

Material
 SEE NOTE
 NOT TO SCALE
 Unit: mm



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Type: CH03-CJ
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 Drawing Number:
 Sheet 1 of 1
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